



## Material Content Data Sheet



<b>Sales Product Name</b>		ICE2A180Z		<b>Issued</b>		29. August 2013		
<b>MA#</b>		MA001086268						
<b>Package</b>		PG-DIP-7-4		<b>Weight*</b>		653.08 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	5.565	0.85	0.85	8521	8521
leadframe	inorganic material	phosphorus	7723-14-0	0.049	0.01		74	
	non noble metal	zinc	7440-66-6	0.194	0.03		297	
	non noble metal	iron	7439-89-6	3.884	0.59		5948	
wire	non noble metal	copper	7440-50-8	157.726	24.15	24.78	241512	247831
	noble metal	gold	7440-57-5	0.178	0.03	0.03	272	272
	encapsulation	organic material	carbon black	1333-86-4	1.424	0.22		2181
encapsulation	plastics	epoxy resin	-	46.049	7.05		70511	
	inorganic material	silicondioxide	60676-86-0	427.261	65.43	72.70	654229	726921
leadfinish	non noble metal	tin	7440-31-5	6.460	0.99	0.99	9891	9891
plating	noble metal	silver	7440-22-4	1.911	0.29	0.29	2926	2926
glue	plastics	epoxy resin	-	0.356	0.05		546	
	noble metal	silver	7440-22-4	2.019	0.31	0.36	3092	3638
*deviation	< 10%					Sum in total:	100,00	1000000

### Important Remarks:

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Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com